

#### Series: SMD Helical Antenna

Description: 860-930MHz Embedded Helical Antenna

#### PART NUMBER: W3136



### Features:

- 860-930MHz
- Impedance 50 Ohm
- Plastic support helical antenna
- Length 29.5mm,
- Gain 2dBi
- SMD Mounting on PCB
- RoHS Compliant

### **Applications:**

- 868MHz and 915MHz ISM Band Systems
- IoT systems
- Metering, Automation
- Security, surveillance
- Remote controls, toys

#### All dimensions are in mm / inches



In the effort to improve our products, we reserve the right to make changes judged to be necessary. For more information:

Issue: 1943

Pulse Worldwide Headquarters 15255 Innovation Drive #100 San Diego, CA 92128 USA Tati 4556 Of KAND

Pulse/Larsen Antennas 18110 SE 34<sup>th</sup> St Bldg 2 Suite 250 Vancouver, WA 98683 USA Tet : 380 944751 Europe Headquarters Pulse GmbH & Do, KG Zeppelinstrasse 15 Herenberg, Germany Pulse (Suzhou) Wireless Products Co, Inc. 99 Huo Ju Road(#29 Bldg,4<sup>th</sup> Phase Suzhou New District Jiangsu Province, Suzhou 215009 PR China Description: 860-930MHz Embedded Helical Antenna



PART NUMBER EGENICAL DATA SHEET

ELECTRICAL SPECIFICATIONS			
Antenna Type	Helical monopole		
Frequency	860-930MHz		
Nominal Impedance	50 Ω		
VSWR	Max 2.5		
Radiation Pattern	Omni		
Gain	2 dBi		
Efficiency	65%		
Polarization	Linear		
Power Withstanding	2W		
MECHANICAL SPECIFICATIONS			
Overall Length	29.5mm		
Weight	2.52g		
Antenna Color / Material	White		
Fix system	SMD+Glue		
Recommended Glue Resinlab EP1320LV Black			
Solder Paste Thickness	Min 0.15mm		
MSL	3		
ENVIRONMENTAL SPECIFICATIONS			
Operating Temperature	-40°C~+85°C		
Storage Temperature	-40°C~+85°C		
RoHS Compliant	Yes		

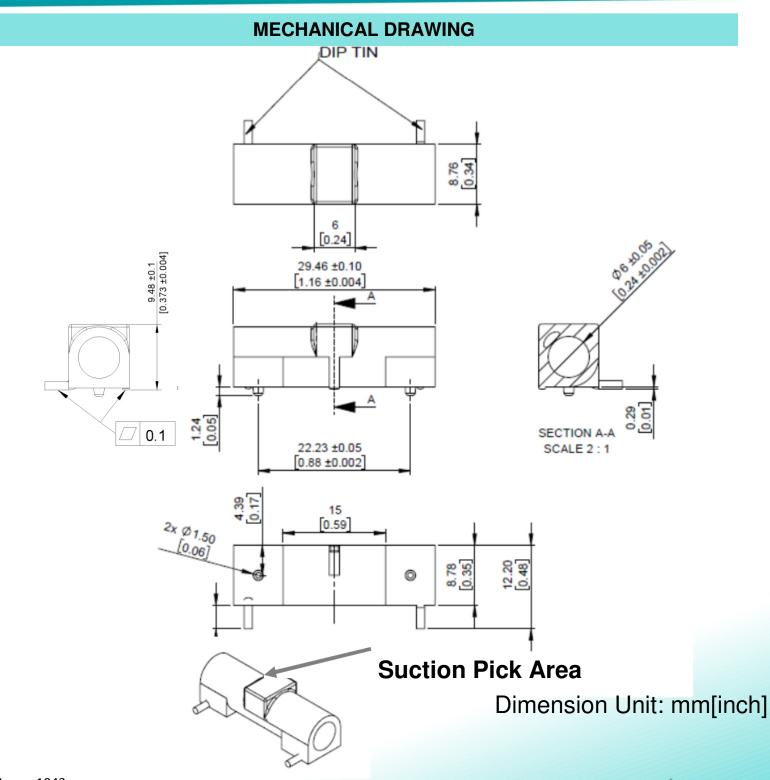
#### **OTHER SPECIFICATIONS**



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3

RoHS



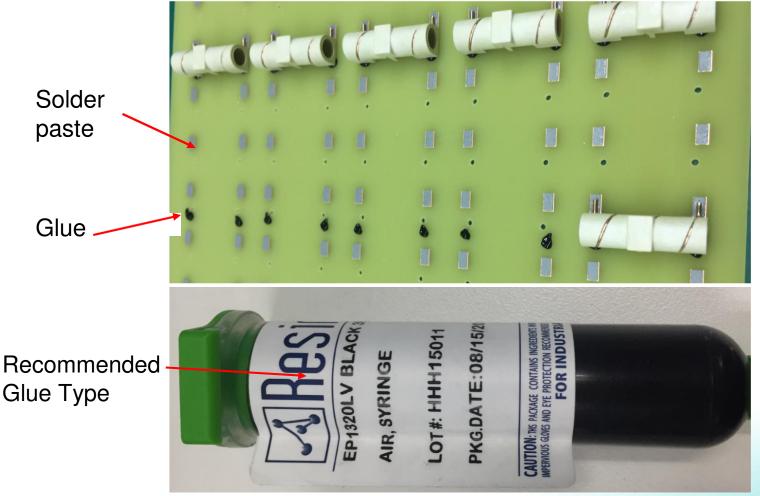
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#### FIX SYSTEM RECOMMENDATION

## Fix system

- 1. SMD process
- 2. Solder paste thickness: minimum 0.15mm
- 3. Glue is required, Recommended Glue: Resinlab EP1320LV Black, usage and position see below recommended area.









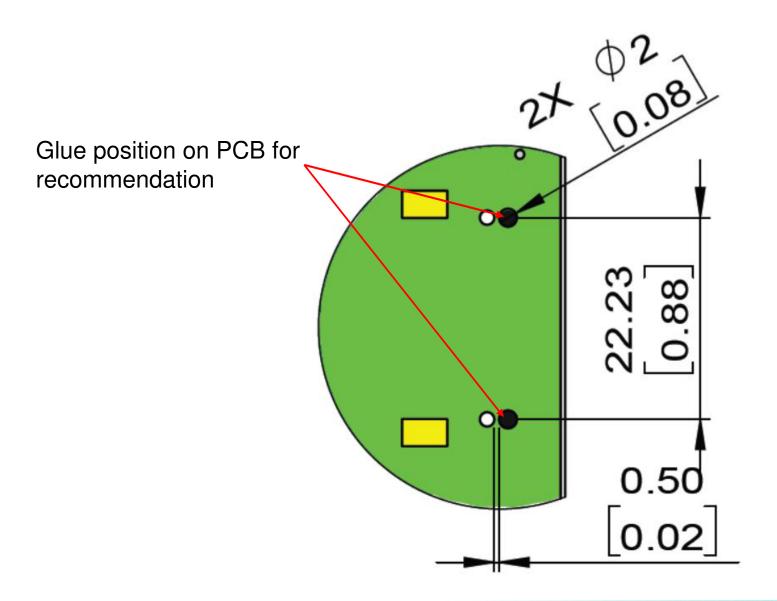
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#### FIX SYSTEM RECOMMENDATION

Fix system

1. Glue position on PCB for recommendation





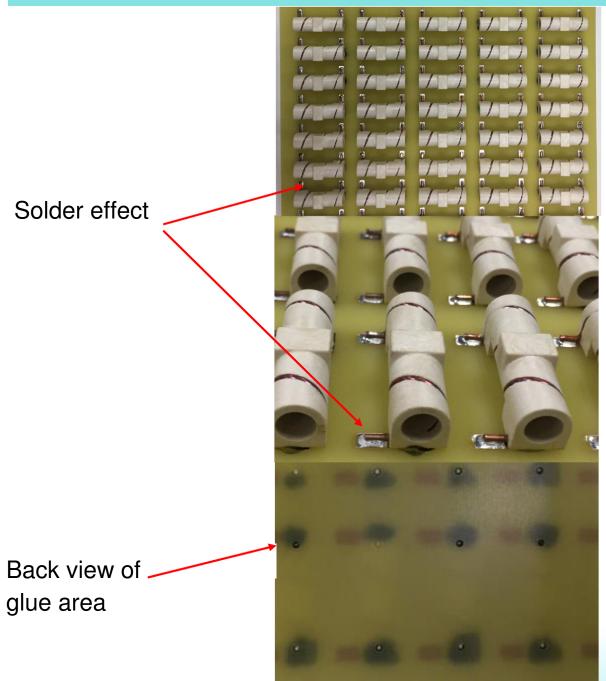


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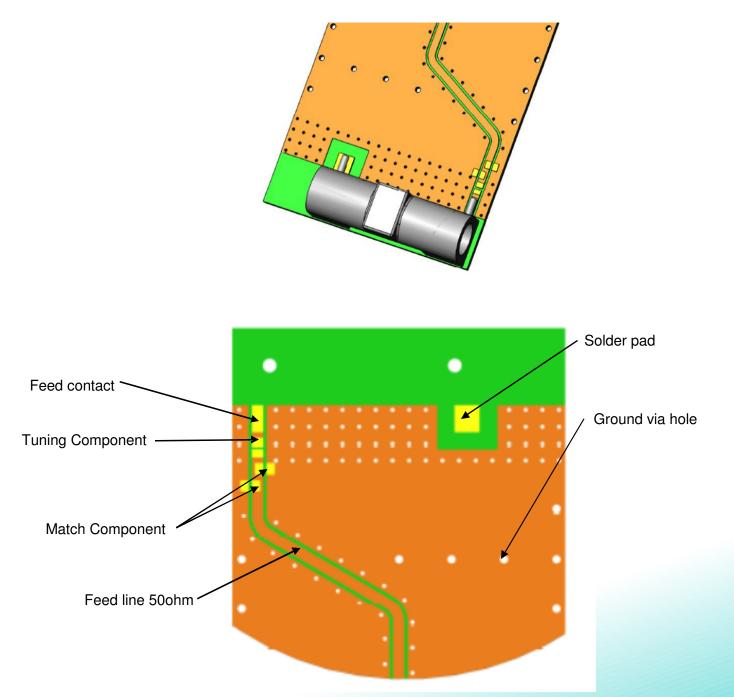
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#### **TEST SETUP**

## PWB Layout for W3136 SMD Helical Antenna







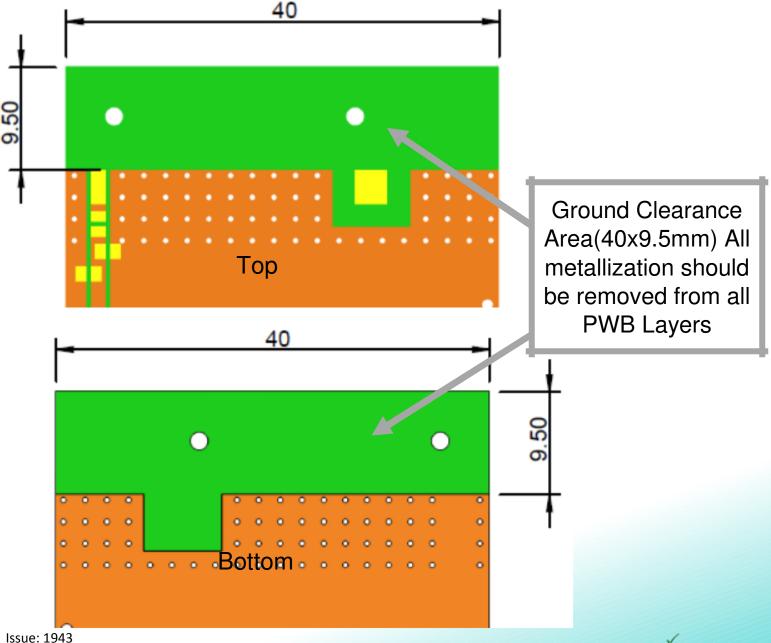
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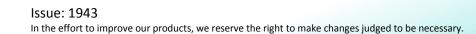
#### **TEST SETUP**

PWB ground clearance area (Top):40x9.5mm PWB ground clearance area (Bottom):40x9.5mm



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RoHS

9

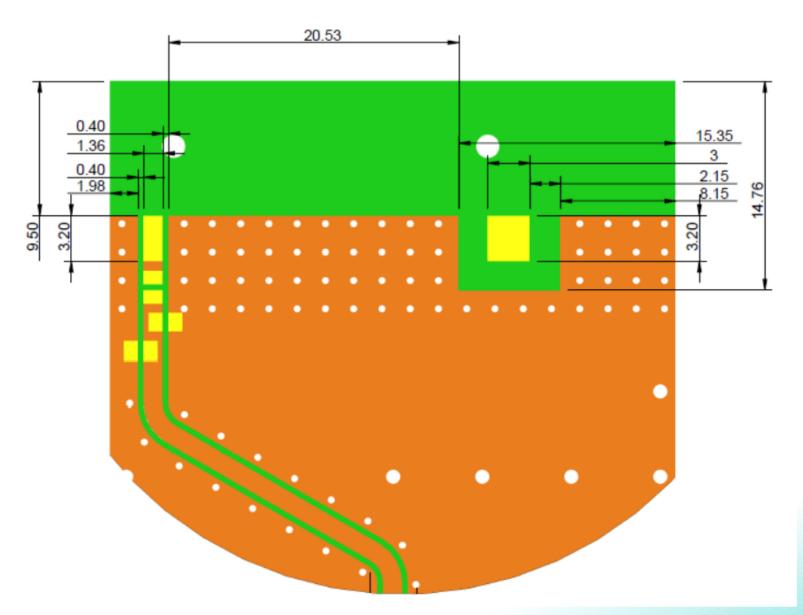


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#### **TEST SETUP**

PWB Pad dimension in top copper





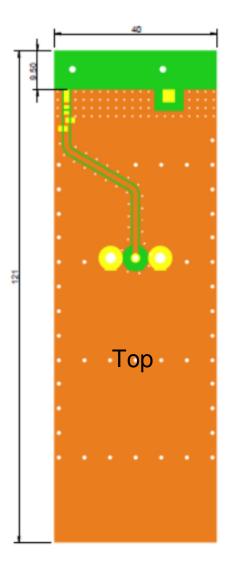


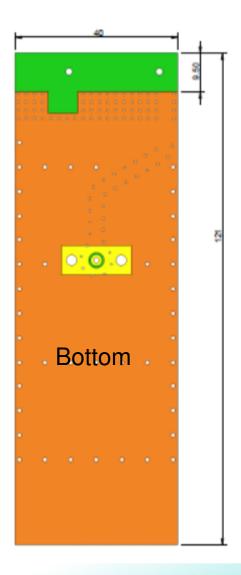
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#### **TEST SETUP**

PWB Layout, Pulse PWB size:121x40mm, Thickness 1.0mm, other size boards can be used depending on customer size.









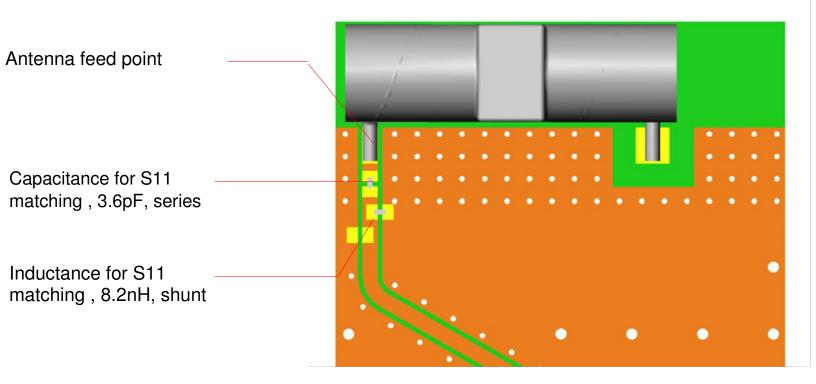
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PWB Layout, Pulse PWB size:121x40mm, Thickness 1.0mm, other size boards can be used depending on customer size.



Note : Exact matching and tuning components value depend on application , board size ,cover etc.





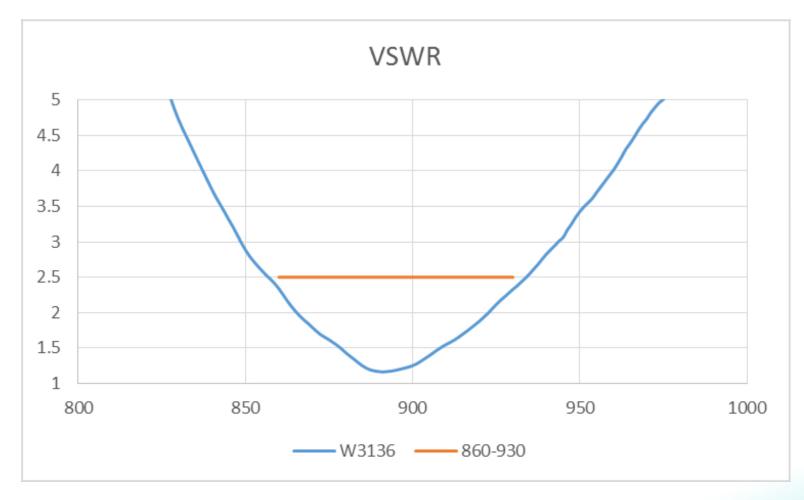
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#### CHARTS

Measured on the 121x40mm test board with tuning and matching circuit









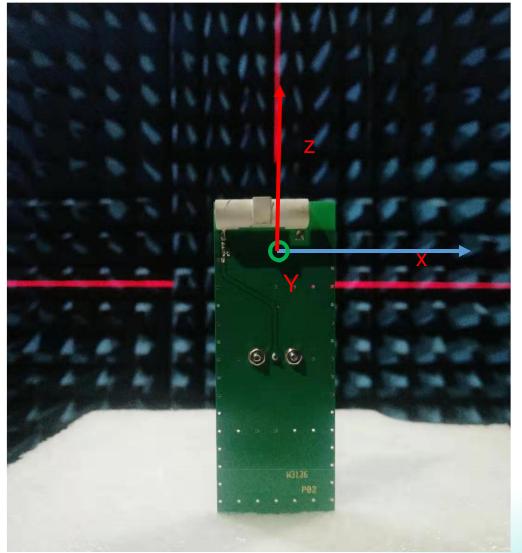
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#### TESTCHARSETSUP

Measured on the 121x40mm test board with tuning and matching circuit.

Test in PSU China Chamber.





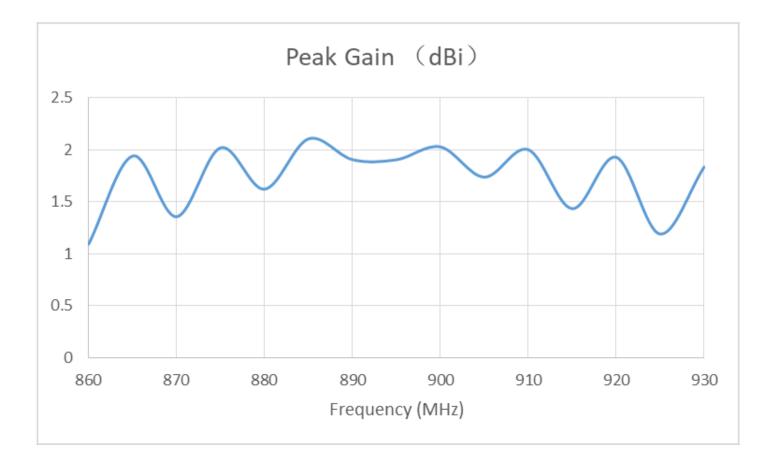


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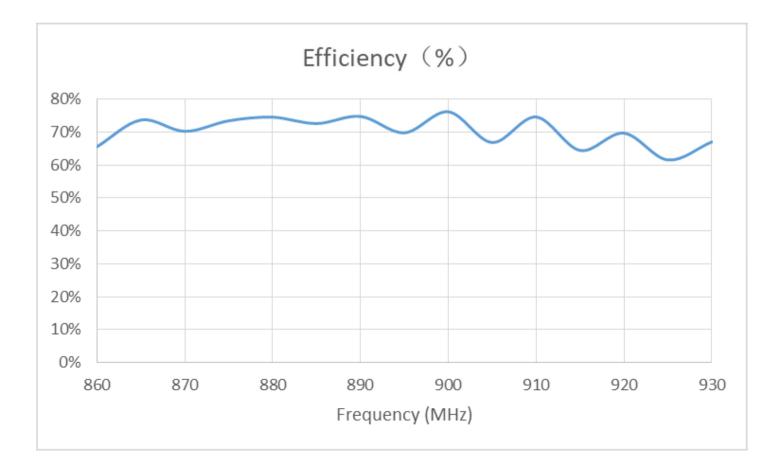


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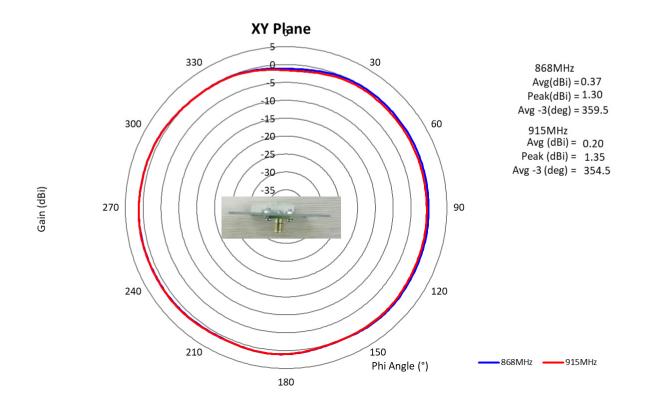
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#### **CHARTS**

## Typical radiation pattern in free space







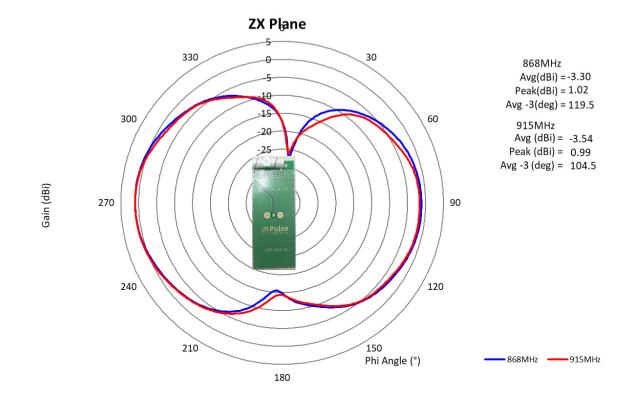
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## Typical radiation pattern in free space







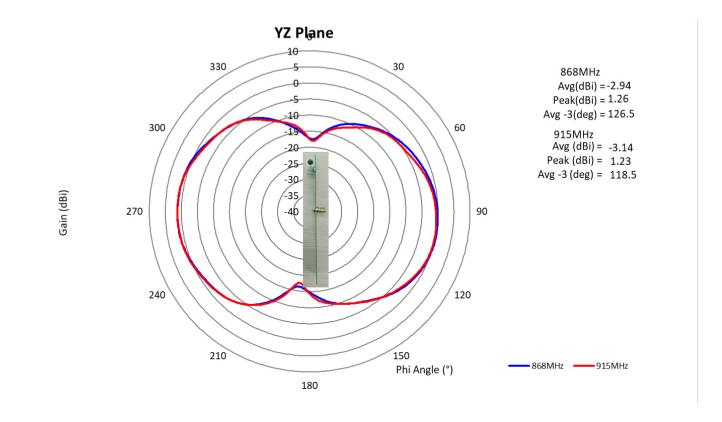
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#### CHARTS

# Typical radiation pattern in free space







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#### **Recommendation for reflow soldering process**

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 °C for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s

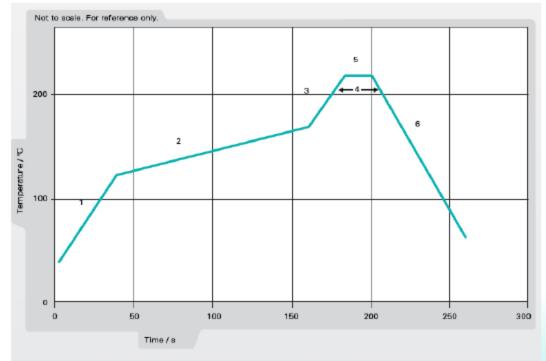


Figure 1. Minimum temperature profile recommendation for reflow soldering process





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#### **Recommendation for reflow soldering process**

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
Б	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

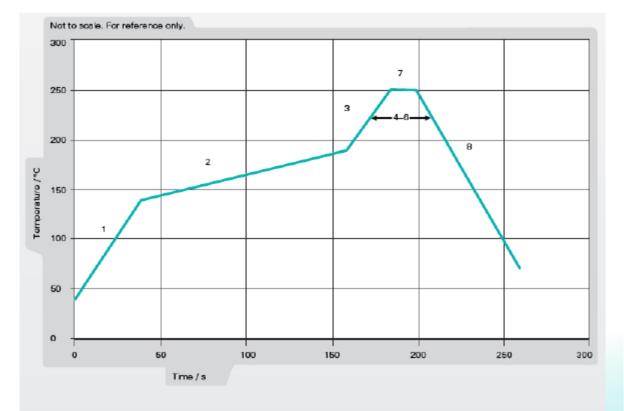


Figure 2. Maximum temperature profile recommendation for reflow soldering process

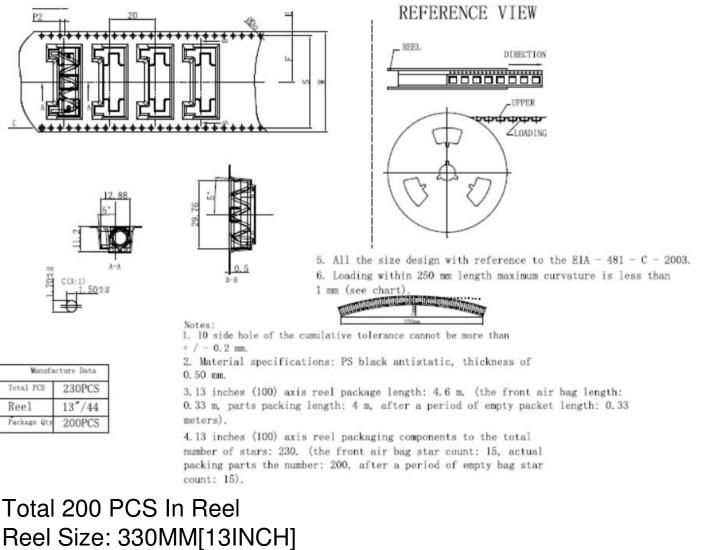




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#### PACKAGING



Total 2 PCS Reel In Package Box Package Box Size:350x350x120mm

